

24. (Amended) A portion to be soldered of an electronic part as claimed in claim 20 wherein the portion to be soldered is a lid of a packaged electronic part.

25. (Amended) A manufacturing method for a solder coated material comprising electroplating a difficult to solder material with a material having excellent solderability to form an electroplated layer, and then passing the difficult to solder material through a molten solder bath to form a hot dip solder plating layer having a thickness of 10 - 50 micrometers on the electroplated layer.

Please add the following claims:

31. A portion to be soldered of an electronic part as claimed in claim 20 wherein the portion to be soldered is a lead frame for an electronic part.

32. A portion to be soldered of an electronic part as claimed in claim 20 wherein the portion to be soldered is a battery terminal.

33. A portion to be soldered of an electronic part as claimed in claim 20 wherein the portion to be soldered is a shield of a module.

34. A portion to be soldered of an electronic part as claimed in claim 20 wherein the portion to be soldered is a connector for a surface mounted part.

35. A method as claimed in claim 25 wherein the difficult to solder material forms part of a lead frame for an electronic part.

36. A method as claimed in claim 25 wherein the difficult to solder material forms part of a lid of a packaged electronic part.

37. A method as claimed in claim 25 wherein the difficult to solder material forms part of a battery terminal.

38. A method as claimed in claim 25 wherein the difficult to solder material forms a part of a shield of a module.

39. A method as claimed in claim 25 wherein the difficult to solder material forms part of a connector for a surface mounted part.

40. A method as claimed in claim 25 wherein the hot dip solder plating layer has a thickness of 15 - 40 micrometers.

41. A method of forming a packaged electronic part comprising performing reflow soldering of a lid including a

substrate of a difficult to solder material, an electroplated layer of a material having excellent solderability formed on the substrate as base plating, and a hot dip solder plating layer formed on the electroplated layer to a package to join the lid to the package.

42. A method as claimed in claim 41 wherein the electroplated layer has a thickness of 0.5 - 5 micrometers and the hot dip solder plating layer has a thickness of 10 - 50 micrometers.

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REMARKS

In response to the Official Action mailed on April 23, 2002, the application has been amended. No new matter has been added. Reconsideration of the rejections of the claims is respectfully requested in view of the above amendments and the following remarks.

Claims 16 - 24 were rejected under 35 USC 102(b) as anticipated by Dale (U.S. Patent No. 3,883,946). This rejection is respectfully traversed.

Independent claim 16 describes a solder coated material including a hot dip solder plating layer formed on an electroplated layer on a substrate of a difficult to solder material, and independent claim 20 describes a portion to be soldered on an electronic part including a hot dip solder plating layer formed